TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSVI)

2SK3767

Switching Regulator Applications

- Low drain-source ON resistance: RDS (ON) = 3.3Ω (typ.)
- High forward transfer admittance: $|Y_{fs}| = 1.6S$ (typ.)
- Low leakage current: IDSS = $100 \,\mu$ A (VDS = 600 V)
- Enhancement mode: $V_{th} = 2.0 \text{ to } 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

| Characteristics | | Symbol | Rating | Unit | |
|--|----------------|------------------|---------|------|--|
| Drain-source voltage | | V_{DSS} | 600 | V | |
| Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$) | | V_{DGR} | 600 | V | |
| Gate-source voltage | | V_{GSS} | ±30 | V | |
| Drain current | DC (Note 1) | ΙD | 2 | ^ | |
| | Pulse (Note 1) | I _{DP} | 5 | Α | |
| Drain power dissipati | on (Tc = 25°C) | P _D | 25 | W | |
| Single pulse avalanche energy (Note 2) | | E _{AS} | 93 | mJ | |
| Avalanche current | | I _{AR} | 2 | Α | |
| Repetitive avalanche energy (Note 3) | | E _{AR} | 4 | mJ | |
| Channel temperature | | T _{ch} | 150 | °C | |
| Storage temperature range | | T _{stg} | -55~150 | °C | |

Thermal Characteristics

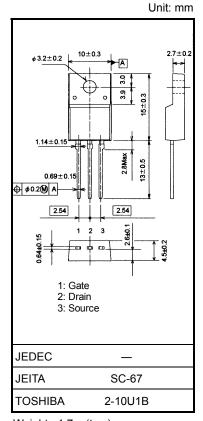
| Characteristics | Symbol | Max | Unit | |
|--|------------------------|------|------|--|
| Thermal resistance, channel to case | R _{th (ch-c)} | 5.0 | °C/W | |
| Thermal resistance, channel to ambient | R _{th (ch-a)} | 62.5 | °C/W | |

Note 1: Ensure that the channel temperature does not exceed 150°C.

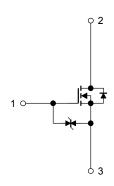
Note 2: VDD = 90 V, Tch = 25°C (initial)) , L = 41mH, RG = 25 Ω , IAR = 2 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Please handle with caution.



Weight: 1.7 g (typ.)



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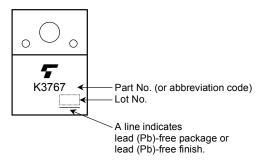
Electrical Characteristics (Ta = 25°C)

| Chara | cteristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|-------------------------------|---------------|----------------------|---|-----|------|-----|------|
| Gate leakage current | | I _{GSS} | $V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$ | _ | _ | ±10 | μА |
| Gate-source breakdown voltage | | V (BR) GSS | $I_G = \pm 10 \ \mu A, \ V_{DS} = 0 \ V$ | ±30 | _ | _ | V |
| Drain cut-off current | | I _{DSS} | V _{DS} = 600 V, V _{GS} = 0 V | _ | _ | 100 | μΑ |
| Drain-source brea | kdown voltage | V (BR) DSS | $I_D = 10$ mA, $V_{GS} = 0$ V | 600 | _ | _ | V |
| Gate threshold vo | tage | V _{th} | V _{DS} = 10 V, I _D = 1 mA | 2.0 | _ | 4.0 | V |
| Drain-source ON I | esistance | R _{DS (ON)} | V _{GS} = 10 V, I _D = 1 A | _ | 3.3 | 4.5 | Ω |
| Forward transfer a | ıdmittance | Y _{fs} | V _{DS} = 10 V, I _D = 1 A | 0.8 | 1.6 | _ | S |
| Input capacitance | | C _{iss} | V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz | _ | 320 | _ | pF |
| Reverse transfer capacitance | | C _{rss} | | _ | 30 | _ | |
| Output capacitance | | Coss | | | 100 | _ | |
| Switching time | Rise time | t _r | $l_D = 1A$ V_{GS} 0 V | | 15 | _ | - ns |
| | Turn-on time | t _{on} | | _ | 55 | | |
| | Fall time | t _f | | | 20 | | |
| | Turn-off time | t _{off} | | _ | 80 | _ | |
| Total gate charge | | Qg | | _ | 9 | _ | |
| Gate-source charge | | Q _{gs} | $V_{DD} \simeq 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 2\text{A}$ | _ | 5 | _ | nC |
| Gate-drain charge | | Q _{gd} | | _ | 4 | | |

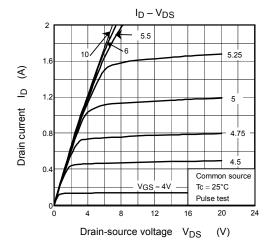
Source-Drain Ratings and Characteristics (Ta = 25°C)

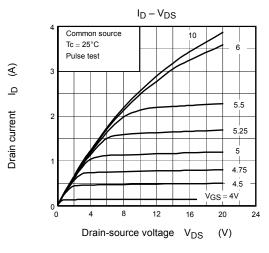
| Characteristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|---|------------------|---------------------------------|-----|------|------|------|
| Continuous drain reverse current (Note 1) | I_{DR} | _ | _ | _ | 2 | Α |
| Pulse drain reverse current (Note 1) | I _{DRP} | _ | _ | _ | 5 | Α |
| Forward voltage (diode) | V _{DSF} | $I_{DR} = 2 A$, $V_{GS} = 0 V$ | _ | _ | -1.7 | V |
| Reverse recovery time | t _{rr} | $I_{DR} = 2 A, V_{GS} = 0 V,$ | _ | 1000 | _ | ns |
| Reverse recovery charge | Qrr | dI _{DR} /dt = 100 A/μs | _ | 3.5 | _ | μС |

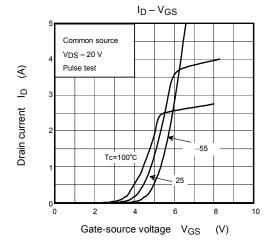
Marking

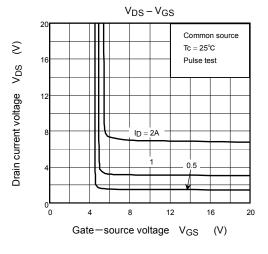


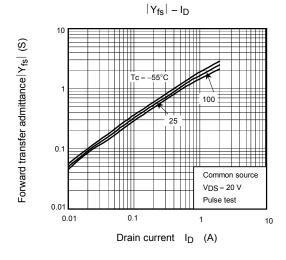
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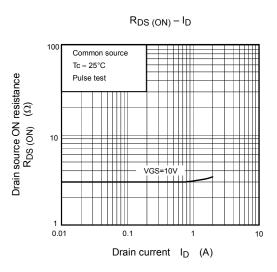




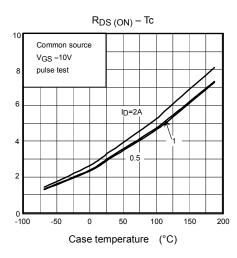








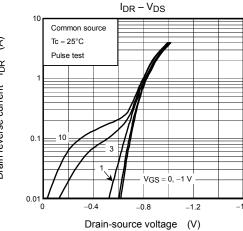
Drain-source ON resistance $R_{DS\,(ON)}\ (\Omega)$



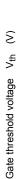
Capacitance – V_{DS}

Drian-source voltage V_{DS} (V)

€ Drain reverse current IDR

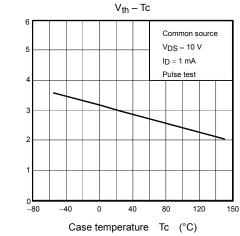


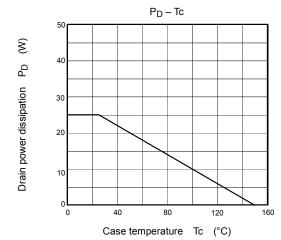
1000 (pF) 100 Capacitance C 10 Common source VGS = 0 V f = 1 MHzTc = 25°C 0.1

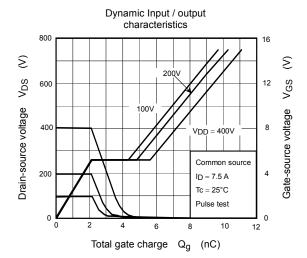


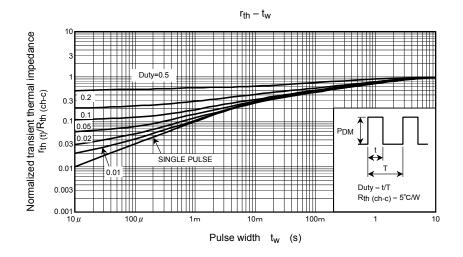
100

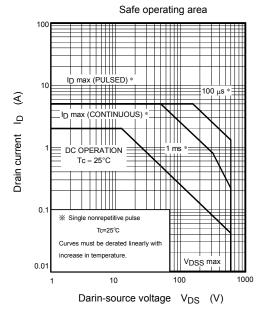
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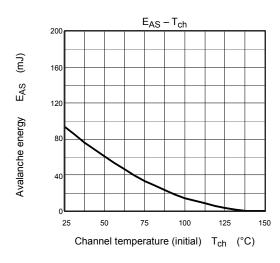


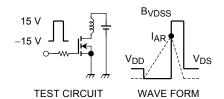












$$\begin{aligned} R_G &= 25~\Omega \\ V_{DD} &= 90~V,~L = 41 mH \end{aligned} \label{eq:RG}$$

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{BVDSS}{BVDSS - VDD} \right)$$

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Handbook" etc...

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